

IN THE CLAIMS

Please cancel claims 1-3, 5-10, 12, and 14-18 without prejudice.

Please add the following new claims.

1-27 (canceled)

28. (New) An apparatus comprising:

a first integrated circuit;

a second integrated circuit residing on top of the first integrated circuit;

a first insulated bond wire connecting the first integrated circuit to the second integrated circuit;

a second insulated bond wire connecting the first integrated circuit to the second integrated circuit.

29. (New) The apparatus of claim 28, wherein the first insulated bond wire crosses over the second insulated bond wire.

30. (New) The apparatus of claim 28, wherein an outer surface of an insulation layer of the first insulated bond wire contacts the second integrated circuit.

31. (New) The apparatus of claim 30, wherein the first insulated bond wire has a tight bond wire pitch angle.

32. (New) The apparatus of claim 28, wherein insulation of each of the first and second insulated bond wires comprises polymer.

33. (New) The apparatus of claim 28, wherein insulation of each of the first and second insulated bond wires is selected from the group consisting of polyvinyl, polytetrafluoroethylene, fluorinated ethylene propylene, and polyimide.

34. (New) The apparatus of claim 28, wherein each of the first and second insulated bond wires is comprised of a metal selected from the group consisting of gold, silver, aluminum, and copper.
35. (New) The apparatus of claim 28, wherein the first integrated circuit, the second integrated circuit, the first insulated bond wire, and the second insulated bond wire reside within a plastic mold.
36. (New) The apparatus of claim 28, wherein an outer surface of an insulation layer of the first insulated bond wire contacts an outer surface of an insulation layer of the second insulated bond wire.
37. (New) The apparatus of claim 28, wherein the first and second integrated circuits include bond pads.
38. (New) The apparatus of claim 28, further comprising a substrate.
39. (New) An integrated circuit assembly comprising a plurality of stacked integrated circuits electrically coupled by a plurality of bond wires, wherein each bond wire has an insulating material coating the bond wire.
40. (New) The integrated circuit assembly of claim 39, wherein the insulating material has a thickness in a range of approximately 0.2 micrometers to 0.6 micrometers.
41. (New) The integrated circuit assembly of claim 39, wherein the insulating material comprises a polymer.
42. (New) The integrated circuit assembly of claim 39, wherein the plurality of bond wires includes bond wires that cross over each other.

43. (New) The integrated circuit assembly of claim 39, wherein the plurality of bond wires includes bond wires that have insulating material that touches at least one of the plurality of stacked integrated circuits.

44. (New) The integrated circuit assembly of claim 39, further comprising a substrate.

45. (New) An apparatus comprising:

- a first integrated circuit;

- a second integrated circuit residing on top of the first integrated circuit;

- an insulated bond wire connecting the first integrated circuit to the second integrated circuit;

- an uninsulated bond wire connecting the first integrated circuit to the second integrated circuit.

46. (New) The apparatus of claim 45, wherein the insulated bond wire crosses over the uninsulated bond wire.

47. (New) The apparatus of claim 45, wherein the uninsulated bond wire touches an outer surface of insulating material of the insulated bond wire.